

**In the Claims:**

Please amend claims 1 and 21 as indicated below. This listing of claims replaces all prior versions.

1. (currently amended) A wafer for fabricating integrated circuits using a stepper, said wafer comprising:

a first region of the wafer, the first region having four sides and having a scribe line along each of the four sides of the first region; and

four alignment targets disposed within said scribe line;

wherein one alignment target is located on each of the four sides of the first region wherein a first alignment target on a first side of the first region and a second alignment target on a second side of the first region opposing said first side are located in mirror-image positions, and further including an overlay~~wherein the second alignment target~~ which has a width that corresponds to a stepper rotational error between the first region and an adjacent second region of the wafer.

2. (previously presented) The wafer as recited in Claim 1 wherein opposing sides of the first region are equal in length, and wherein an alignment target is located at each mid-point of a side of first region.

3. (previously presented) The wafer as recited in Claim 1 wherein an alignment target is located at each corner of the first region.

4. (original) The wafer as recited in Claim 1 wherein said alignment targets are formed according to a positive resist process.

5. (original) The wafer as recited in Claim 1 wherein said alignment targets are formed according to a negative resist process.

6. (canceled)

7.(original) The wafer as recited in Claim 1 wherein each of said alignment targets comprise a plurality of rectangles.

8– 20. (canceled)

21. (currently amended) A semiconductor structure, comprising:

a wafer;

a plurality of four-sided integrated circuit regions, separated by scribe lines disposed on a first surface of the wafer; and

at least one alignment target disposed in a first scribe line, the first scribe line being a common region between a first stepper shot and a second stepper shot;

wherein the second stepper shot overlays an alignment target on the at least one alignment target disposed in the first scribe line and the resulting overlay target has a width that corresponds to a stepper rotational error between the first stepper shot and the second stepper shot.